Infrared Photo Diode Specification

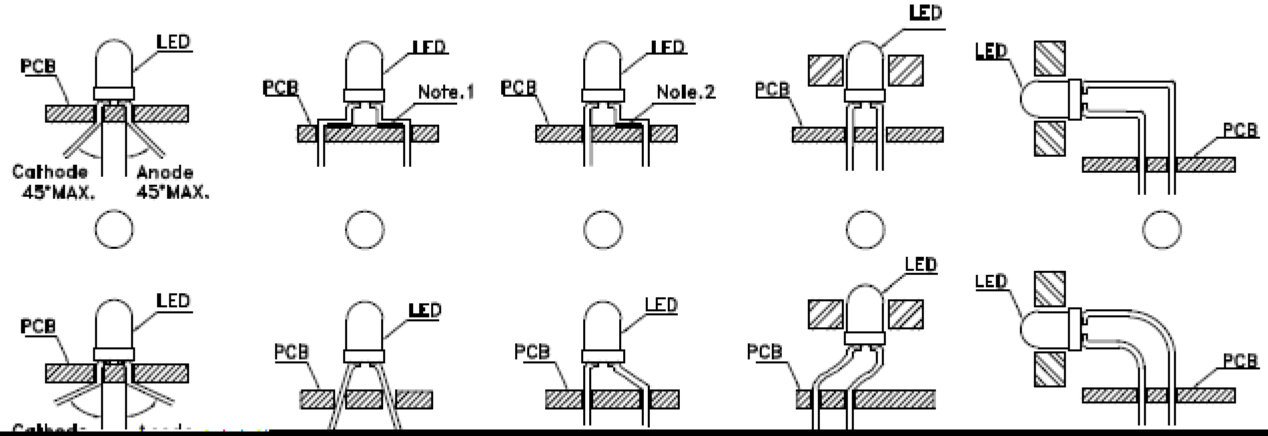
●Commodity: Infrared Photo diode

●Intensity Bin Limits (VR=5V, Ee=1mW/cm^2, =940nm)

BIN CODE	Min.(uA)	Max.(uA)
36	53	64
37	64	77
38	77	92

LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).



[redacted]

ounting method

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

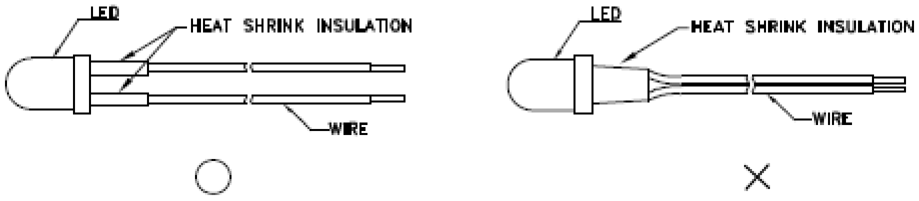
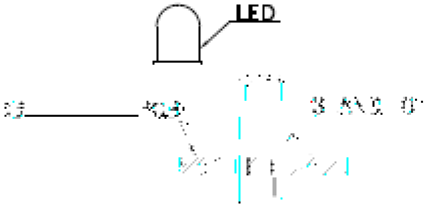
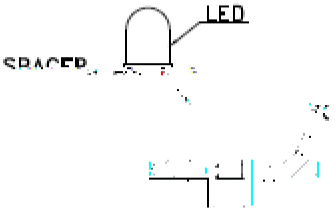


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

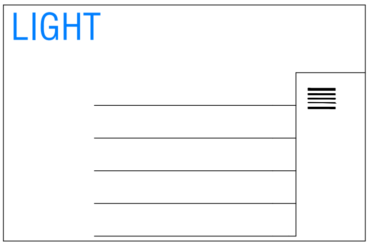


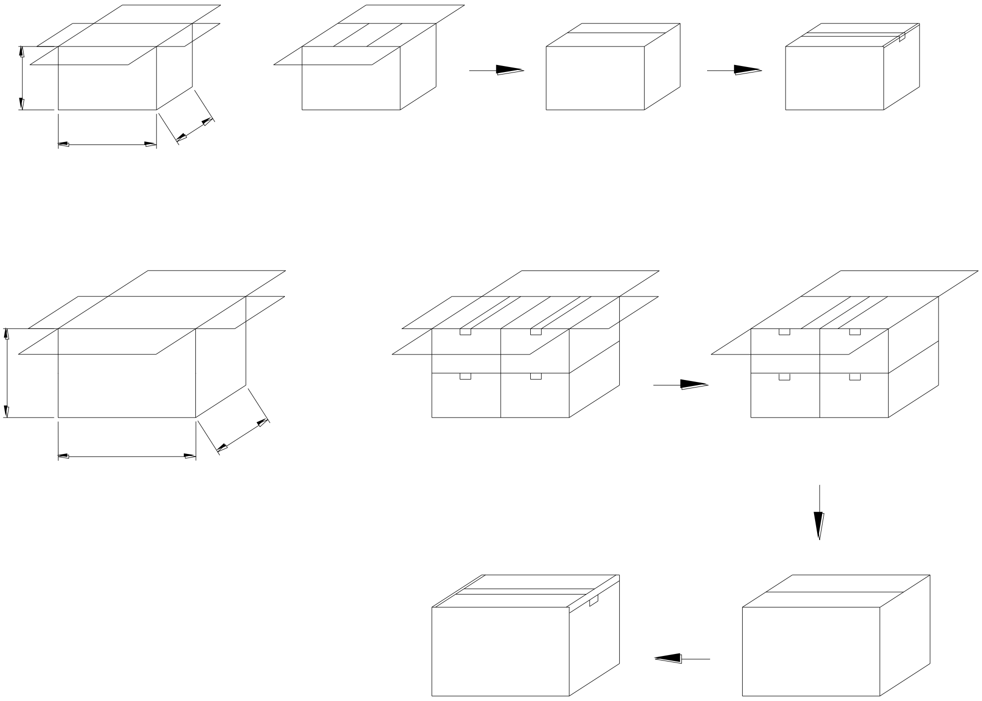
g. 3



g. 4

PACKAGE





Bag minimum volume (pcs / Bag)	Bag volume (pcs / Bag)	Inner box volume (Bag / box)	Outer carton volume (Box / Carton)
500	1000	10	4